

35. (New) The composition of claim 33, wherein at least 60 wt% of ethylenically unsaturated monomers present in said composition comprise three or more ethylenically unsaturated bonds.

36. (New) The composition of claim 33, wherein at least 80 wt% of ethylenically unsaturated monomers present in said composition comprise three or more ethylenically unsaturated bonds.

37. (New) The composition of claim 33, wherein all ethylenically unsaturated monomers present in said composition comprise three or more ethylenically unsaturated bonds.

*SubD2*  
*C1*  
~~38. (New) The composition of claim 33, wherein said composition comprises, relative to the total weight of the composition, 7-25wt% of said dipentaerythritol penta(meth)acrylate.~~

39. (New) The composition of claim 38, wherein said composition comprises, relative to the total weight of the composition, 40-75 wt% of said epoxy compound.

40. (New) The composition of claim 39, wherein said composition comprises, relative to the total weight of the composition, 5-35 wt% of said polyol.

41. (New) A process for photo-fabricating a three-dimensional object comprising: selectively curing a photo-curable resin according to claim 33.

42. (New) A three-dimensional object formed by the process of claim 41.

#### REMARKS

Upon entry of this Amendment, claims 1-2, 19, and 21-42 will be pending of which claims 1, 30, and 33 are independent. Claims 33-42 have been added. Support for new claims 33-42 can be found throughout the application as filed. For instance, new claim 33 corresponds to the formulation recited in claim 1 as originally filed, except that components (A), (C), and (E) have been even further defined. Support for present component (A) can be found, *e.g.*, on page 10, lines 23-28, of the